



Material Composition Declaration

EPC2014C

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	3.4 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	2.9085	86.68	88.89	866776
	Silicon oxide	7631-86-9	0.0114	0.34		3394
	Silicon nitride	12033-89-5	0.0037	0.11		1098
	Gallium nitride	25617-97-4	0.0137	0.41		4072
	Aluminum	7429-90-5	0.0221	0.66		6584
	Aluminum nitride	24304-00-5	0.0033	0.10		984
	Titanium	7440-32-6	0.0006	0.02		188
	Titanium nitride	25583-20-4	0.0020	0.06		594
	Copper	7440-50-8	0.0007	0.02		218
	Tungsten	7440-33-7	0.0008	0.02		231
	Polyimide		0.0161	0.48		4792
Under Bump Metal	Titanium	7440-32-6	0.0005	0.02	1.32	157
	Nickel	7440-02-0	0.0156	0.46		4647
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.0282	0.84		8413
Solder Bump	Tin	7440-31-5	0.3201	9.54	9.79	95406
	Silver	7440-22-4	0.0082	0.24		2446
	Copper	7440-50-8	0.0000	0.00		0
Sum in total:			3.4	100.00	100	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.